

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

| | | | | | | | | |
|---|--|----------------|---------------|-------------|----------------|--|---------------|-------|
| Title of Invention | [WAFER STRUCTURE AND BUMPING PROCESS THEREOF] | | | | | | | |
| Application Number : | | | | | | | | |
| Date : | | | | | | | | |
| First Named Applicant: | Mr. Min-Lung Huang | | | | | | | |
| Confirmation Number: | | | | | | | | |
| Attorney Docket Number: | 11579-US-PA | | | | | | | |
| <p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I , the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p> | | | | | | | | |
| <table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Dr. Belinda Lee Registered Number: 46,863</td><td>/Belinda Lee/</td><td>Agent</td></tr></table> | | | Submitted By: | Elec. Sign. | Sign. Capacity | Dr. Belinda Lee Registered Number: 46,863 | /Belinda Lee/ | Agent |
| Submitted By: | Elec. Sign. | Sign. Capacity | | | | | | |
| Dr. Belinda Lee Registered Number: 46,863 | /Belinda Lee/ | Agent | | | | | | |

| Documents being submitted: | Files |
|----------------------------|---|
| us-assignment | 11579-usassn.xml us-assignment.xsl us-assignment.dtd 11579assignment1.tif 11579assignment2.tif |
| us-request | 11579-usrequ.xml us-request.dtd us-request.xsl |
| us-fee-sheet | 11579-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd |
| application-body | 11579-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd 11579us0001.tif 11579us0002.tif 11579us0003.tif 11579us0004.tif 11579us0005.tif 11579us0006.tif 11579us0007.tif |
| us-declaration | 11579declaration1.tif |
| us-declaration | 11579declaration2.tif |
| Comments | |

Please be kindly advised that the indicated fees of this EFS application is intended to be paid by credit card. However, in the event that the payment through credit card is unsuccessful, the Commissioner is authorized to charge the required fees in connection with this application to: Deposit Account No. 50-2620 (Order No. 11579-US-PA), Deposit Account Name: Jianq Chyun Intellectual Property Office, Authorized User Name: Belinda Lee, E-mail: belinda@jcipgroup.com.tw; usa@jcipgroup.com.tw